

USB Type-C Connector

1 Scope:

1.1 Contents

This specification covers the requirements for product performance, test methods and quality assurance provisions of TE Connectivity USB type C connector.

Applicable product description and part numbers are as shown in Appendix 1.

2. Applicable Documents:

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

2.1 TE Connectivity Specification:

A. 109-5000: Test Specification, General Requirements for Test Methods

B. 501-115169: Qualification Test Report

2.2 Commercial Standard and Specification:

A. ANSI/EIA 364-C

B. Universal Serial Bus Type-C Connector and Cables Assemblies Compliance Document.

3. Requirements:

3.1 Design and Construction:

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2 Materials:

A. Contact (Plug & Receptacle)

Material: Copper alloy

B. Housing (Plug & Receptacle)

Thermo Plastic, UL 94 V-0

C. Shell (Plug & Receptacle)

Material: Stainless steel

3.3 Ratings:

- A. Voltage Rating: 30 V Max.
- B. Current Rating:
 - (1). VBUS/GND pins: 1.25A Max
 - (2). VCONN pins: 1.25A Max.
 - (3). Signal pins contact: 0.25A Min.
- C. Temperature Rating: -30°C to 85°C (Including temperature rising)
- D. Storage Temperature: -30°C to 85°C

3.4 Performance Requirements and Test Descriptions:

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Fig.1. All tests shall be performed in the room temperature, unless otherwise specified.

Temperature:15°C ~ 35°C Humidity :25% ~ 85% R.H. Pressure :650mmHg ~ 800mmHg

DR		DATE	APVD	DATE
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3.5 Test Requirements and Procedures Summary

Table.1

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¹ Separate Report



Table.1(End	.)	
Durability	EIA 364-09 10,000 cycles	No evidence of physical damage
Durability (Preconditioning)	EIA 364-09 50 cycles	No evidence of physical damage
Reseating	Manually unplug/plug the connector. Perform 3 such cycles	No evidence of physical damage
Environmental		
Temperature Life	EIA-364-17, Method A 105°C, 120hrs	No evidence of physical damages Meet LLCR requirement Insulation > 100M Ω Min.
Temperature Life (Preconditioning)	EIA-364-17, Method A 105°C, 72hrs	No evidence of physical damages Meet LLCR requirement Insulation > 100MΩ Min.
Thermal Shock	EIA-364-32, Method A, Condition I, duration A-4 10 cycles with the exception of exposure times. Place a thermocouple in the center of the largest mass component of the connector that is in the center of the test chamber to ensure that the contacts reach the temperature extremes before ramping to the other temperature (-55°-+85°C, 10 cycles).	No evidence of physical damages Meet LLCR requirement Insulation > 100MΩ Min.
Cyclic Temperature and Humidity	 EIA-364-31, Method III, w/o optional cold shock and vibration. Exceptions per EIA-364-1000: Cycle between 25°C/80%RH and 65°C/50%RH. Ramp 0.5hr, dwell 1hr, dwell starts when conditions are stabilized. 24 cycles total Allowable variation ±3°C and ±3%RH 	No evidence of physical damages Meet LLCR requirement Insulation > 100MΩ Min.
Vibration Mixed Flowing	 EIA-364-28, Condition VII-D, 15min in each of 3 mutually perpendicular directions. Both mating halves should be fixed rigidly. (Power Spectral Density 0.02g²/Hz, Overall rms 3.10g) EIA-364-65, class IIA, 112hrs unmated, 56hrs mated 	No evidence of physical damages and no discontinuity longer than 1 microsecond. No evidence of physical damages
Gas	(168hrs total).	Meet LLCR requirement Insulation > 100M Ω Min.
Thermal Disturbance	Cycle the mated connector pair 10 times between 15°C and 85°C. - ramp > 2°C/min - dwell > 5 mins (ensure contacts reach temperature) - Humidity not controlled - Allowable variation ±3°C	No evidence of physical damages Meet LLCR requirement Insulation > 100MΩ Min.
Other		[
Solderability	Category 3 Steam Age RMA Class 1 flux immerse in molten solder at a temperature of +255°C ± 5°C at rate of 25.4 mm ± 6.35 mm per second. Hold in solder for 5 +0/-0.5 seconds. To include solder pins and mounting pads.	Solderable area shall have a minimum of 95% solder coverage.

NOTE: (1) Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Prequalification Test Sequence shown in table 2.



108-115152

3.6 Product Qualification Test Sequence

Table.2

Test	Α	В	С	D	Е	G ²	Н	³
Critical Dimensions						1		
Low Level Contact	1,4,6	1,4,6,8	1,4,6	1,4,6,8,10	2,7			
Resistance	1,4,0	1,4,0,0	1,4,0	1,4,0,0,10	,			
Durability					5			
Durability	2	2	2	2				
(Preconditioning)	2	2	2	2				
Insertion Force					3			
Extraction Force					4,6			
Temperature Life	3							
Temperature Life			3	3				
(Preconditioning)			5	5				
Reseating	5	7		9				
Thermal Shock		3						
Cyclic Temperature		5						
and Humidity		5						
Vibration			5					
Mixed Flowing Gas				5				
Thermal Disturbance				7				
Dielectric					1 0			
Withstanding Voltage					1,8			
Insulation Resistance					9			
Current Rating							1	
Solderability								1
Sample Size	5	5	5	5	5	5	5	5

Signal Integrity Testing

Test Requirements and Test Sequence as per USB Type C Compliance Document.

² To be reported in Critical Dimension Inspection Report

³ Additional test, not part of USB Type C Compliance Requirements



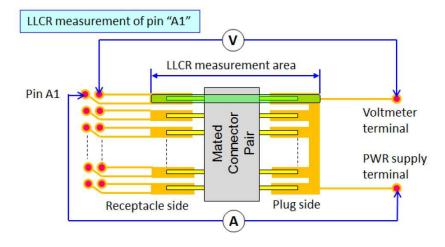


Figure 1: Typical Contact Resistance Measurement

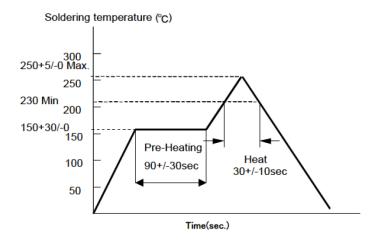


Figure 2. Recommended reflow temp profile



The applicable product descriptions and part numbers are as shown in Appendix.1.

Product Part No.	Description			
2340901-*	USB TYPE C 2.0 CONN REV MID- MOUNT ONE ROW SMT WITH 0.035mm OFFSET			

(Prepared by) Rambo Zhang(Checked by) Richard Ma

(Approved by) Simon Li

Date <u>23-Jan-2019</u> Date

<u>23-Jan-2019</u>

Date <u>23-Jan-2019</u>

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